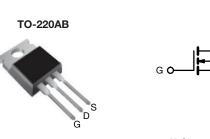
SiHP33N60E

Vishay Siliconix



E Series Power MOSFET



S
N-Channel MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} max. (Ω) at 25 °C	$V_{GS} = 10 V$	0.099			
Q _g max. (nC)	150				
Q _{gs} (nC)	24				
Q _{gd} (nC)	42				
Configuration	Single				

FEATURES

- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	ТО-220АВ
Lead (Pb)-free	SiHP33N60E-E3
Lead (Pb)-free and Halogen-free	SiHP33N60E-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	600	N/	
Gate-Source Voltage			V _{GS}	± 30	V	
Continuous Drain Current (T _J = 150 °C)	V at 10 V	, T _C = 25 °C	- I _D	33		
	V _{GS} at 10 V	$T_{C} = 25 \text{ °C}$ $T_{C} = 100 \text{ °C}$		21	А	
Pulsed Drain Current ^a			I _{DM}	88		
Linear Derating Factor				2.2	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	793	mJ	
Maximum Power Dissipation			P _D	278	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	$V_{DS} = 0 V \text{ to } 80 \% V_{DS}$		-1) / / -14	70		
Reverse Diode dV/dt ^d	•		dV/dt	12	V/ns	
Soldering Recommendations (Peak temperature) ^c	for 10 s			300	°C	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 7.5 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D,\,dI/dt$ = 100 A/µs, starting T_J = 25 °C.

S24-0062-Rev. H, 22-Jan-2024

1

(Pb) RoHS

COMPLIANT

HALOGEN

FREE



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	0.45	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static		•		·			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	600	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Cata Sauraa Laakaga	1	$V_{GS} = \pm 20 V$		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30 V$	-	-	± 1	μA
Zara Cata Valtaga Drain Current	1	V _{DS} =	= 600 V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 V	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 \text{ °C}$		-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 16.5 A	-	0.083	0.099	Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = 30 V, I _D = 16.5 A		-	11	-	S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$ f = 1 MHz		-	3508	-	pF
Output Capacitance	C _{oss}			-	156	-	
Reverse Transfer Capacitance	C _{rss}			-	6	-	
Effective Output Capacitance, Energy Related ^b	C _{o(er)}	$V_{GS} = 0 V, V_{DS} = 0 V to 480 V$		-	136	-	
Effective Output Capacitance, Time Related ^c	C _{o(tr)}			-	468	-	
Total Gate Charge	Qg			-	100	150	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V I _D = 16.5 A, V _{DS} = 480 V		-	24	-	nC
Gate-Drain Charge	Q _{gd}			-	42	-	1
Turn-On Delay Time	t _{d(on)}	V _{DD} = 480 V, I _D = 16.5 A		-	28	56	
Rise Time	t _r			-	60	90	ns
Turn-Off Delay Time	t _{d(off)}		$R_g = 9.1 \Omega, V_{GS} = 10 V$		99	150	
Fall Time	t _f	1		-	54	80	
Gate Input Resistance	Rg	f = 1 MHz, open drain		0.2	0.7	1.0	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol		-	33	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	88	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 16.5 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			-	503	1006	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S,$ dl/dt = 100 A/µs, V _R = 20 V		-	8.5	17	μC
Reverse Recovery Current	I _{RRM}			-	26	-	Α

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

c. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

2



SiHP33N60E

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

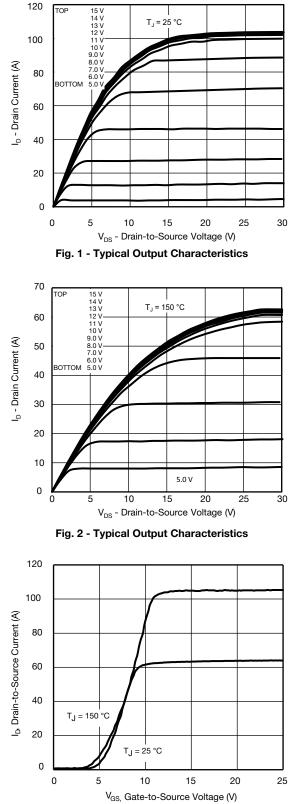


Fig. 3 - Typical Transfer Characteristics

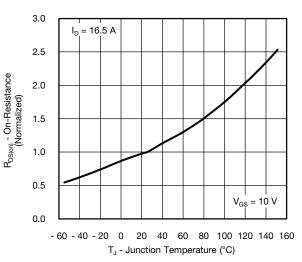


Fig. 4 - Normalized On-Resistance vs. Temperature

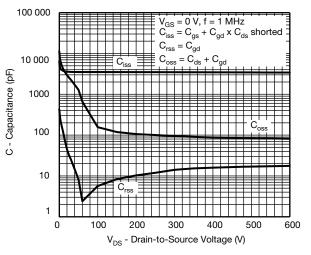
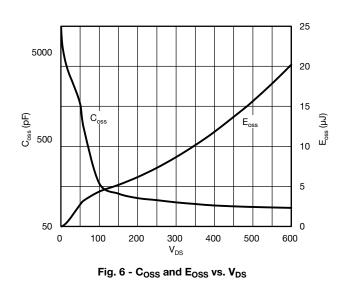


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



S24-0062-Rev. H, 22-Jan-2024

3

Document Number: 91523





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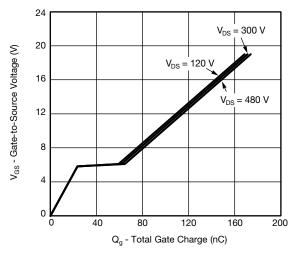


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

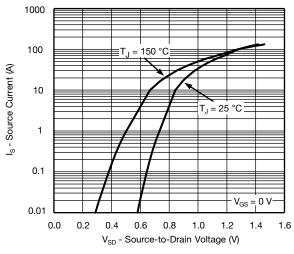


Fig. 8 - Typical Source-Drain Diode Forward Voltage

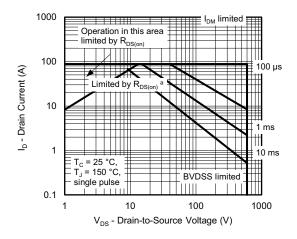


Fig. 9 - Maximum Safe Operating Area

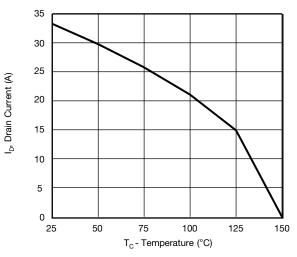


Fig. 10 - Maximum Drain Current vs. Case Temperature

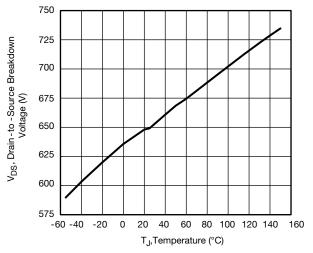


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature

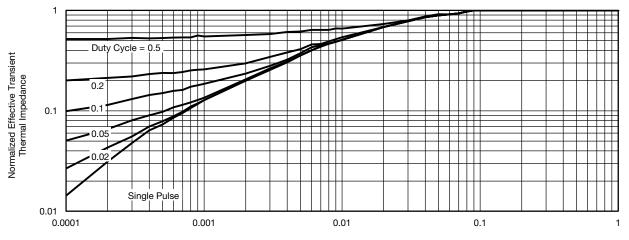
S24-0062-Rev. H, 22-Jan-2024

4



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Square Wave Pulse Duration (s) Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

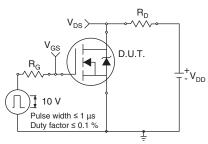


Fig. 13 - Switching Time Test Circuit

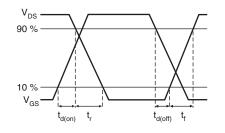


Fig. 14 - Switching Time Waveforms

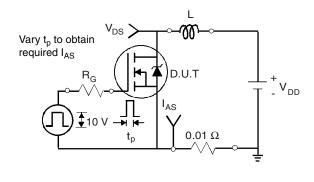


Fig. 15 - Unclamped Inductive Test Circuit

S24-0062-Rev. H, 22-Jan-2024

5

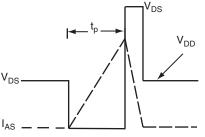


Fig. 16 - Unclamped Inductive Waveforms

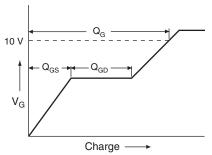
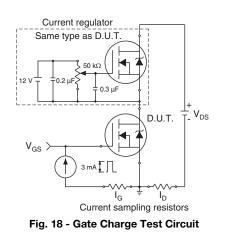


Fig. 17 - Basic Gate Charge Waveform





Peak Diode Recovery dV/dt Test Circuit

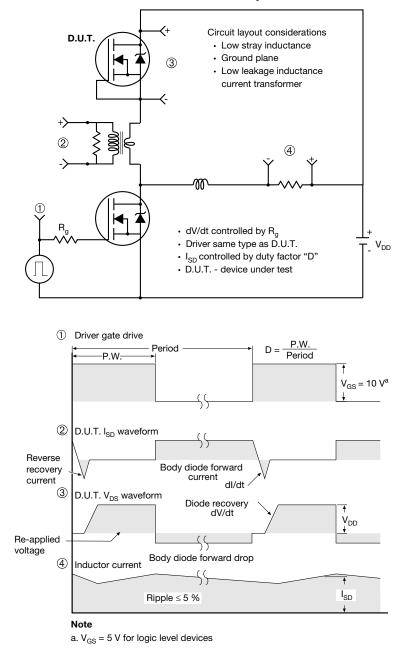


Fig. 19 - For N-Channel

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